

Description

The DMG3404L uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

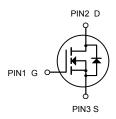
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SOT-23

General Features

 $V_{DS} = 30V I_{D} = 5.8A$

 $R_{DS(ON)}$ < 28m Ω @ V_{GS} =10V



N-Channel MOSFET

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMG3404L	SOT-23	HXY MOSFET	3000

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage	30	V
V _G S	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous	5.8	Α
Ідм	Drain Current-Pulsed (Note 1)	18.4	Α
P_{D}	Maximum Power Dissipation	1	W
ТЈ,Тѕтс	Operating Junction and Storage Temperature Range	-55 To 150	${\mathbb C}$
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	125	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
$\triangle BV_{DSS}/\triangle T$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.023		V/°C	
Dagger	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =4A		22	28	mΩ	
R _{DS(ON)}	Static Dialii-Source On-Resistance	V _{GS} =4.5V , I _D =3A		26	32		
$V_{GS(th)}$	Gate Threshold Voltage	\/=\/	1.0	1.5	2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-4.2		mV/°C	
1	Drain Source Leekage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =4A		7		S	
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.3	4.6	Ω	
Qg	Total Gate Charge (4.5V)			5.0	6.9		
Qgs	Gate-Source Charge	V_{DS} =15V , V_{GS} =4.5V , I_{D} =4A		1.1	2.2	nC	
Q _{gd}	Gate-Drain Charge			2.6	2.8		
$T_{d(on)}$	Turn-On Delay Time			2	4		
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω		34.4	62	20	
$T_{d(off)}$	Turn-Off Delay Time	I _D =4A		13.2	26	ns	
Tf	Fall Time			4.8	9.6		
Ciss	Input Capacitance			420	582		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		60	87	pF	
Crss	Reverse Transfer Capacitance			53	71		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,4}	\/-=\/-=0\/	-		4.6	Α
Ism	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			18.4	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V
t _{rr}	Reverse Recovery Time			8.7		nS
Qrr	Reverse Recovery Charge	$I_F = 4A$, $dI/dt = 100A/\mu s$, $T_J = 25$ °C		2.3		nC

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

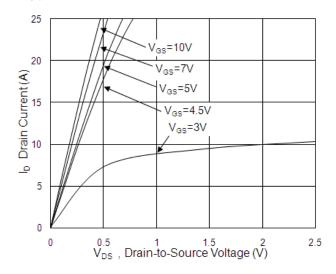


Fig.1 Typical Output Characteristics

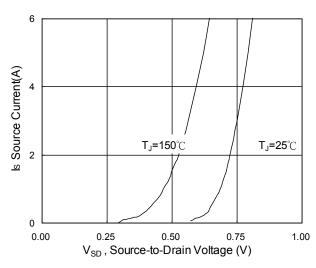


Fig.3 Forward Characteristics Of Reverse

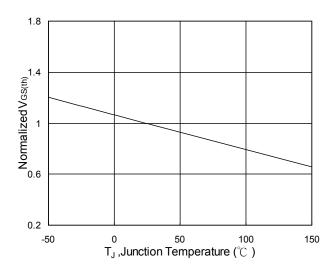


Fig.5 Normalized V_{GS(th)} vs. T_J

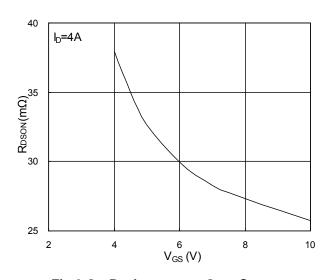


Fig.2 On-Resistance vs. Gate-Source

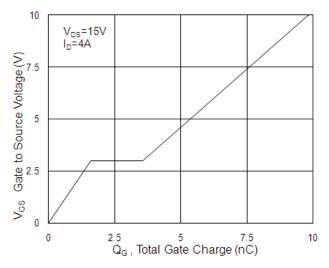


Fig.4 Gate-Charge Characteristics

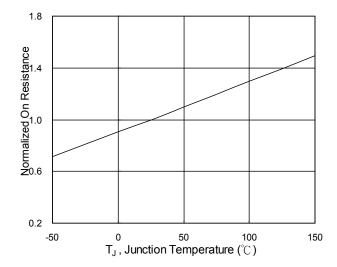
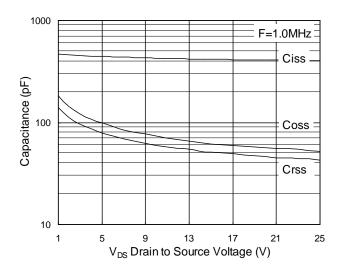


Fig.6 Normalized R_{DSON} vs. T_J



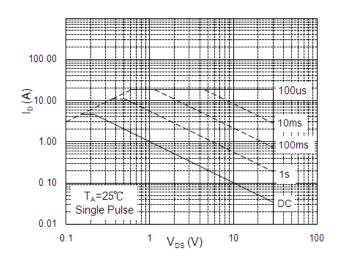


Fig.7 Capacitance

Fig.8 Safe Operating Area

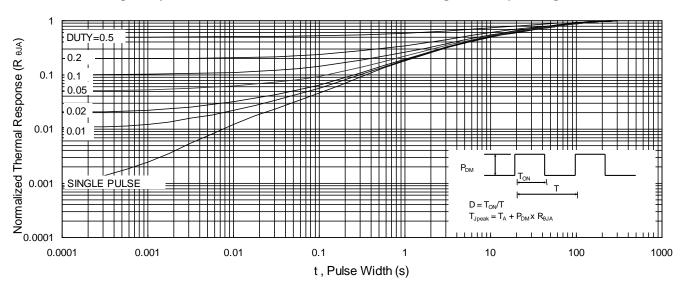


Fig.9 Normalized Maximum Transient Thermal Impedance

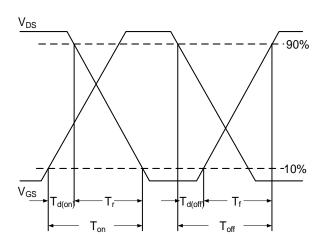


Fig.10 Switching Time Waveform

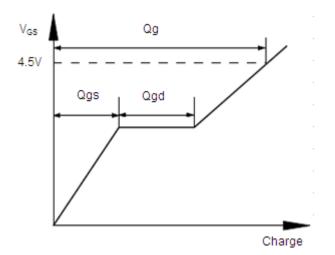
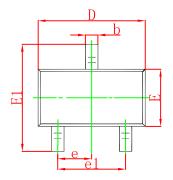
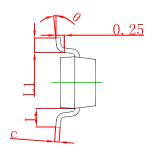


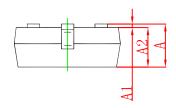
Fig.11 Gate Charge Waveform



SOT-23 Package Outline Dimensions

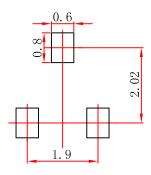






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550	REF	0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

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